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ABSTRACT OF THE DISCLOSURE

A circuit component built-in module of the present invention includes an insulating substrate formed of a mixture comprising 70wt% to 95wt% of an inorganic filler and a thermosetting resin, a plurality of wiring patterns formed on at least a principal plane of the insulating substrate, a circuit component arranged in an internal portion of the insulating substrate and electrically connected to the wiring patterns, and an inner via formed in the insulating substrate for electrically connecting the plurality of wiring patterns. Thus, a highly reliable circuit component built-in module having high-density circuit components can be obtained.